

Title (en)

ELECTRONIC CHIP CARRIER PACKAGE AND METHOD OF MAKING THEREOF.

Title (de)

GEHÄUSE FÜR EINEN ELEKTRONISCHEN CHIPTRÄGER UND HERSTELLUNGSVERFAHREN.

Title (fr)

CONDITIONNEMENT DE SUPPORT D'UNE PUCE ELECTRONIQUE ET PROCEDE POUR LA FABRICATION DE CELUI-CI.

Publication

EP 0681741 A4 19960605 (EN)

Application

EP 95901084 A 19941031

Priority

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- US 16275093 A 19931129

Abstract (en)

[origin: WO9515007A1] A method and design for packaging electronic chip devices, especially devices intended for radio frequency (RF) and microwave frequencies above 900 MHz is disclosed. An array of metal leads (100) are bonded between two layers of a sheet polymer composite that have been cut to form frames (40, 130) in such a way that the metal leads (100) extend from outside to inside of the single frame shape formed by a pressure and heat bonding step. The polymer composite frame serves the dual purpose of holding the leads in a desired configuration for later assembly and testing steps both inside and outside of its area, and of providing a microwave quality, low insertion loss, low permittivity and electrical insulation function between leads and ground planes. This dual purpose is provided in a uniquely cost-effective way that makes it of particular value for packaging high frequency electronic components intended for the growing consumer and commercial applications market.

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Citation (search report)

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- [A] DE 2423662 A1 19741205 - RAYTHEON CO
- [Y] PATENT ABSTRACTS OF JAPAN vol. 8, no. 119 (E - 248) 5 June 1984 (1984-06-05)
- [Y] BALDE J W; AMEY D I: "Special Feature New Chip Carrier Package Concepts", COMPUTER, IEEE, US, vol. 10, no. 12, 1 December 1977 (1977-12-01), US, pages 58 - 68, XP002000206, ISSN: 0018-9162, DOI: 10.1109/C-M.1977.217602
- [A] PATENT ABSTRACTS OF JAPAN vol. 10, no. 117 (E - 400) 2 May 1986 (1986-05-02)
- See references of WO 9515007A1

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